

NTHD3100C

MOSFET – Power, Complementary, ChipFET

20 V, +3.9 A /-4.4 A

Features

- Complementary N-Channel and P-Channel MOSFET
- Small Size, 40% Smaller than TSOP-6 Package
- Leadless SMD Package Provides Great Thermal Characteristics
- Trench P-Channel for Low On Resistance
- Low Gate Charge N-Channel for Test Switching
- Pb-Free Packages are Available

Applications

- DC-DC Conversion Circuits
- Load Switch Applications Requiring Level Shift
- Drive Small Brushless DC Motors
- Ideal for Power Management Applications in Portable, Battery Powered Products

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DS}	20	V
Gate-to-Source Voltage	N-Ch	V_{GS}	± 12	V
	P-Ch		± 8.0	
N-Channel Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D	A
			2.9	
	$t \leq 10$ s	$T_A = 85^\circ\text{C}$	2.1	
P-Channel Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D	A
			-3.2	
	$t \leq 10$ s	$T_A = 85^\circ\text{C}$	-2.3	
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D	W
			1.1	
	$t \leq 5$ s	$T_A = 25^\circ\text{C}$	3.1	
Pulsed Drain Current (Note 1)	N-Ch	$t = 10$ μs	I_{DM}	A
	P-Ch	$t = 10$ μs	-13	
Operating Junction and Storage Temperature		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$
Source Current (Body Diode)		I_S	2.5	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

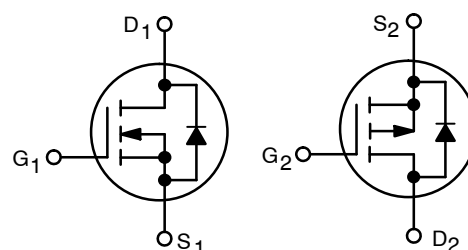
1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



ON Semiconductor®

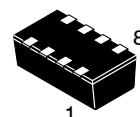
<http://onsemi.com>

$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	I_D MAX
N-Channel 20 V	58 m Ω @ 4.5 V	3.9 A
	77 m Ω @ 2.5 V	
P-Channel -20 V	64 m Ω @ -4.5 V	-4.4 A
	85 m Ω @ -2.5 V	



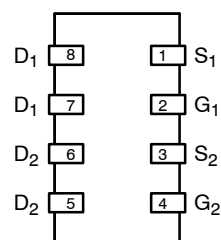
N-Channel MOSFET

P-Channel MOSFET

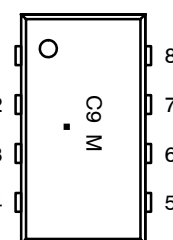


**ChipFET
CASE 1206A
STYLE 2**

PIN CONNECTIONS



MARKING DIAGRAM



C9 = Specific Device Code
M = Month Code
■ = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

NTHD3100C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	113	$^{\circ}\text{C/W}$
Junction-to-Ambient – $t \leq 10$ s (Note 2)	$R_{\theta JA}$	60	$^{\circ}\text{C/W}$

2. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	N/P	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS (Note 3)							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	N	$V_{GS} = 0$ V	$I_D = 250$ μA	20		V
		P		$I_D = -250$ μA	-20		
Zero Gate Voltage Drain Current	I_{DSS}	N	$V_{GS} = 0$ V, $V_{DS} = 16$ V	$T_J = 25^{\circ}\text{C}$		1.0	μA
		P	$V_{GS} = 0$ V, $V_{DS} = -16$ V			-1.0	
		N	$V_{GS} = 0$ V, $V_{DS} = 16$ V	$T_J = 125^{\circ}\text{C}$		5.0	
		P	$V_{GS} = 0$ V, $V_{DS} = -16$ V			-5.0	
Gate-to-Source Leakage Current	I_{GSS}	N	$V_{DS} = 0$ V, $V_{GS} = \pm 12$ V			± 100	nA
		P	$V_{DS} = 0$ V, $V_{GS} = \pm 8.0$ V			± 100	

ON CHARACTERISTICS

 (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	N	$V_{GS} = V_{DS}$	$I_D = 250$ μA	0.6	1.2	V
		P		$I_D = -250$ μA	-0.45	-1.5	
Drain-to-Source On Resistance	$R_{DS(on)}$	N	$V_{GS} = 4.5$ V, $I_D = 2.9$ A		58	80	m Ω
		P	$V_{GS} = -4.5$ V, $I_D = -3.2$ A		64	80	
		N	$V_{GS} = 2.5$ V, $I_D = 2.3$ A		77	115	
		P	$V_{GS} = -2.5$ V, $I_D = -2.2$ A		85	110	
Forward Transconductance	g_{FS}	N	$V_{DS} = 10$ V, $I_D = 2.9$ A		6.0		S
		P	$V_{DS} = -10$ V, $I_D = -3.2$ A		8.0		

CHARGES AND CAPACITANCES

Input Capacitance	C_{ISS}	N	$f = 1$ MHz, $V_{GS} = 0$ V	$V_{DS} = 10$ V		165	pF
		P		$V_{DS} = -10$ V		680	
Output Capacitance	C_{OSS}	N		$V_{DS} = 10$ V		80	
		P		$V_{DS} = -10$ V		100	
Reverse Transfer Capacitance	C_{RSS}	N		$V_{DS} = 10$ V		25	
		P		$V_{DS} = -10$ V		70	
Total Gate Charge	$Q_{G(TOT)}$	N		$V_{GS} = 4.5$ V, $V_{DS} = 10$ V, $I_D = 2.9$ A		2.3	nC
		P		$V_{GS} = -4.5$ V, $V_{DS} = -10$ V, $I_D = -3.2$ A		7.4	
Threshold Gate Charge	$Q_{G(TH)}$	N		$V_{GS} = 4.5$ V, $V_{DS} = 10$ V, $I_D = 2.9$ A		0.2	
		P		$V_{GS} = -4.5$ V, $V_{DS} = -10$ V, $I_D = -3.2$ A		0.6	
Gate-to-Source Gate Charge	Q_{GS}	N		$V_{GS} = 4.5$ V, $V_{DS} = 10$ V, $I_D = 2.9$ A		0.4	
		P		$V_{GS} = -4.5$ V, $V_{DS} = -10$ V, $I_D = -3.2$ A		1.4	
Gate-to-Drain "Miller" Charge	Q_{GD}	N		$V_{GS} = 4.5$ V, $V_{DS} = 10$ V, $I_D = 2.9$ A		0.7	
		P		$V_{GS} = -4.5$ V, $V_{DS} = -10$ V, $I_D = -3.2$ A		2.5	

3. Pulse Test: pulse width ≤ 250 μs , duty cycle $\leq 2\%$.

NTHD3100C

ELECTRICAL CHARACTERISTICS (continued) ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	N/P	Test Conditions	Min	Typ	Max	Unit
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	$t_{d(ON)}$	N	$V_{GS} = 4.5\text{ V}, V_{DD} = 10\text{ V},$ $I_D = 2.9\text{ A}, R_G = 2.5\ \Omega$		6.3		ns
Rise Time	t_r				10.7		
Turn-Off Delay Time	$t_{d(OFF)}$				9.6		
Fall Time	t_f				1.5		
Turn-On Delay Time	$t_{d(ON)}$	P	$V_{GS} = -4.5\text{ V}, V_{DD} = -10\text{ V},$ $I_D = -3.2\text{ A}, R_G = 2.5\ \Omega$		5.8		
Rise Time	t_r				11.7		
Turn-Off Delay Time	$t_{d(OFF)}$				16		
Fall Time	t_f				12.4		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	N	$V_{GS} = 0\text{ V}, T_J = 25^\circ\text{C}$	$I_S = 2.5\text{ A}$		0.8	1.15	V
		P		$I_S = -2.5\text{ A}$		-0.8	-1.2	
Reverse Recovery Time	t_{RR}	N	$V_{GS} = 0\text{ V},$ $dI_S / dt = 100\text{ A}/\mu\text{s}$	$I_S = 1.5\text{ A}$		12.5		ns
		P		$I_S = -1.5\text{ A}$		13.5		
Charge Time	t_a	N		$I_S = 1.5\text{ A}$		9.0		
		P		$I_S = -1.5\text{ A}$		9.5		
Discharge Time	t_b	N		$I_S = 1.5\text{ A}$		3.5		
		P		$I_S = -1.5\text{ A}$		4.0		
Reverse Recovery Charge	Q_{RR}	N		$I_S = 1.5\text{ A}$		6.0		nC
		P		$I_S = -1.5\text{ A}$		6.5		

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL N-CHANNEL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)

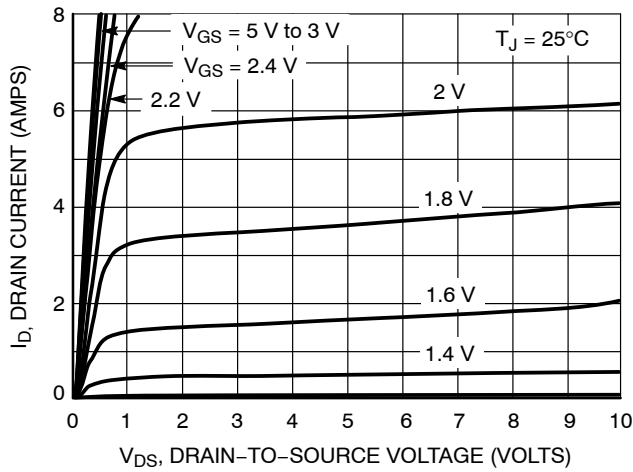


Figure 1. On-Region Characteristics

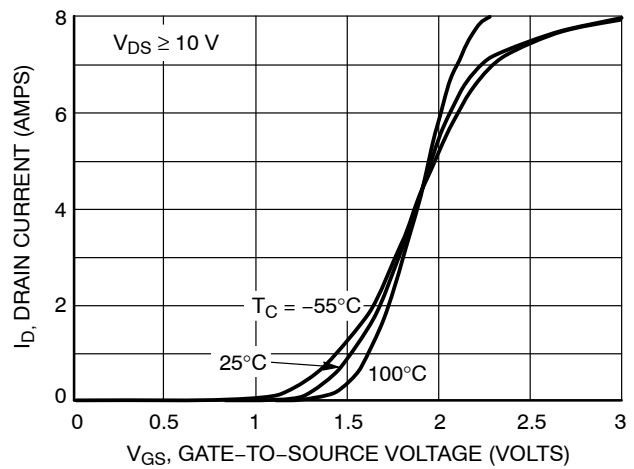


Figure 2. Transfer Characteristics

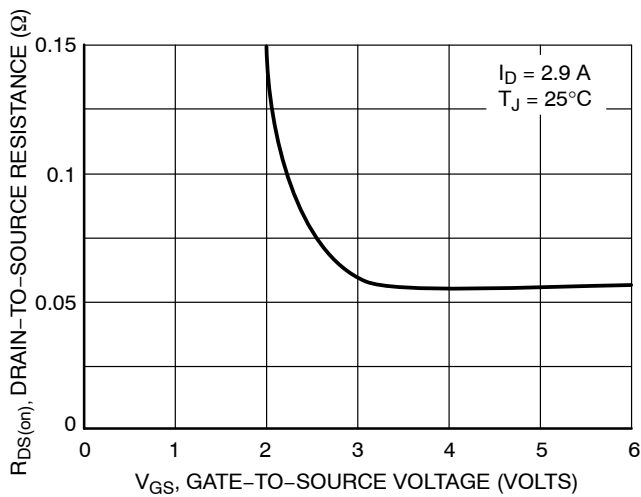


Figure 3. On-Resistance vs. Gate-to-Source Voltage

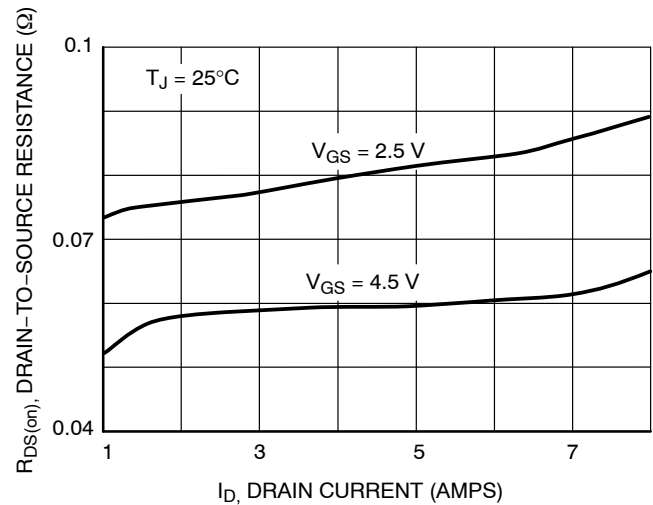


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

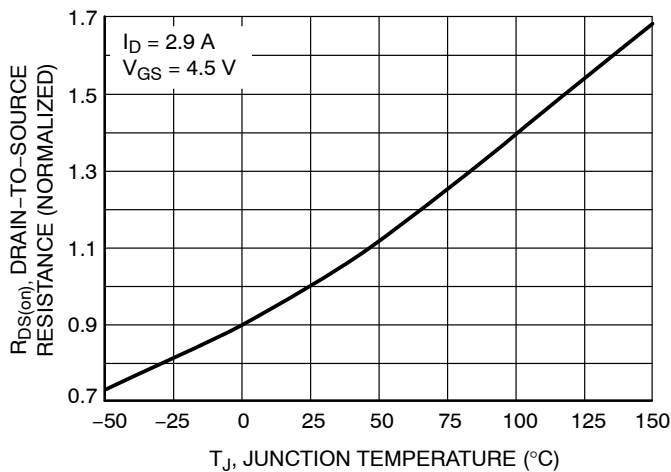


Figure 5. On-Resistance Variation with Temperature

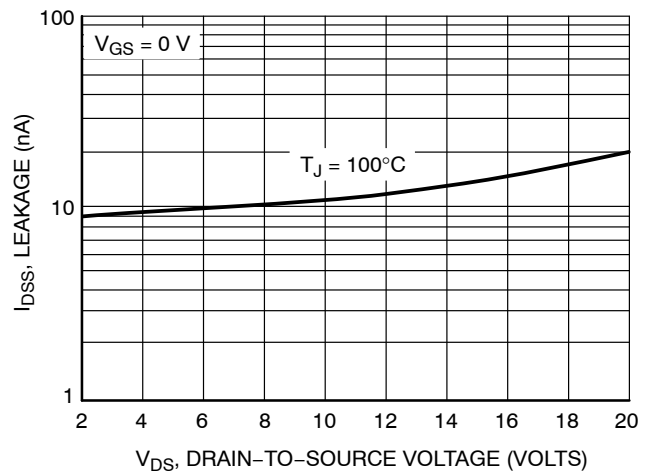


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL N-CHANNEL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)

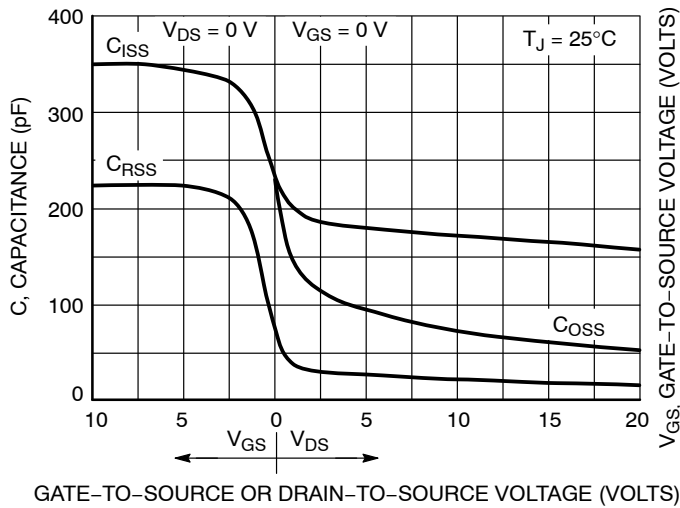


Figure 7. Capacitance Variation

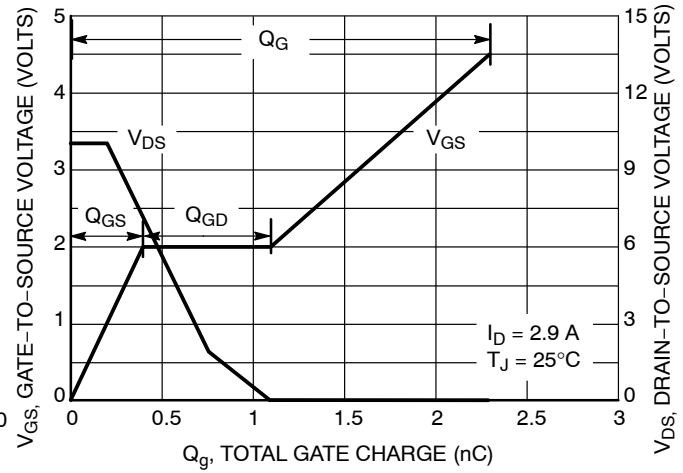


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

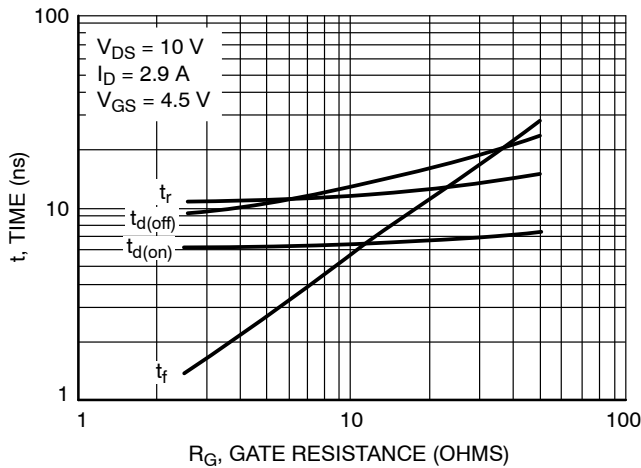


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

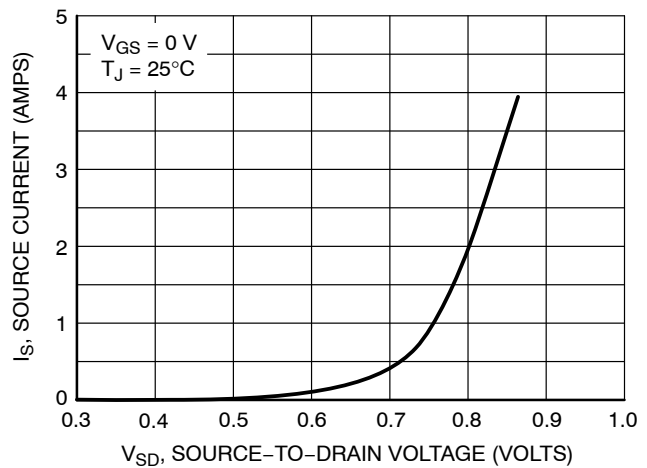


Figure 10. Diode Forward Voltage vs. Current

TYPICAL P-CHANNEL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)

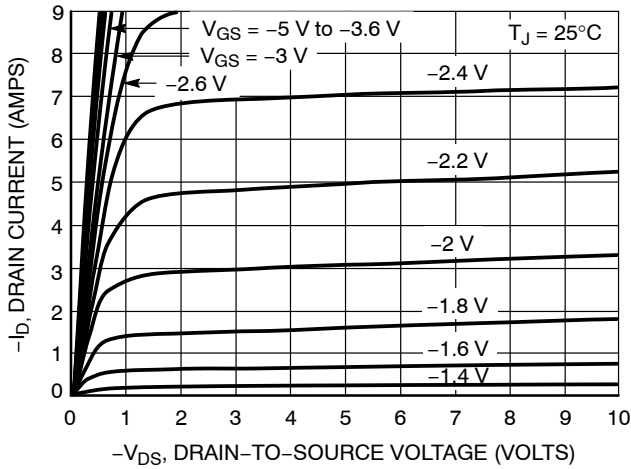


Figure 11. On-Region Characteristics

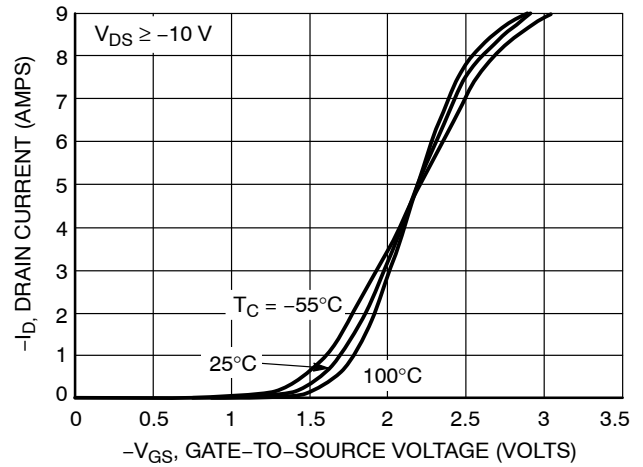


Figure 12. Transfer Characteristics

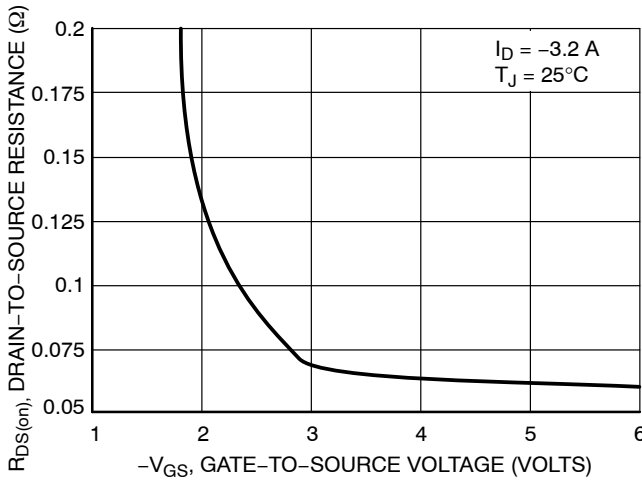


Figure 13. On-Resistance vs. Gate-to-Source Voltage

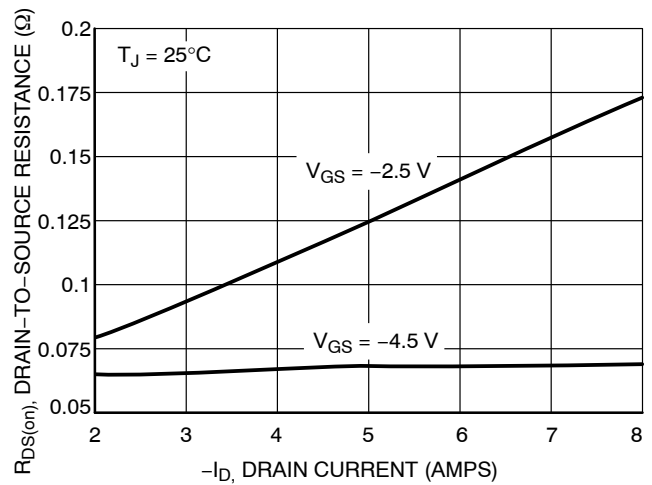


Figure 14. On-Resistance vs. Drain Current and Gate Voltage

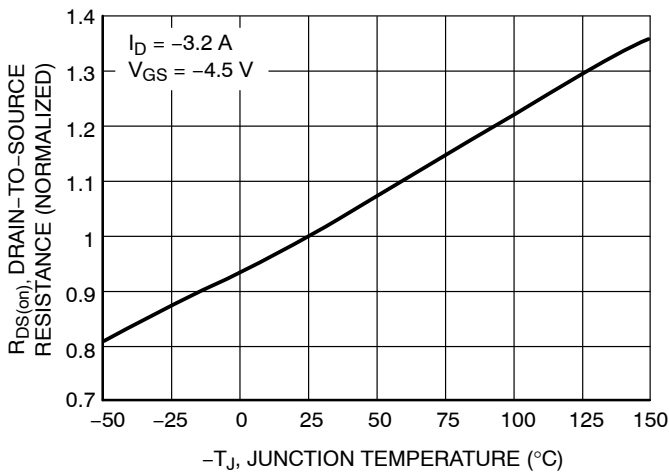


Figure 15. On-Resistance Variation with Temperature

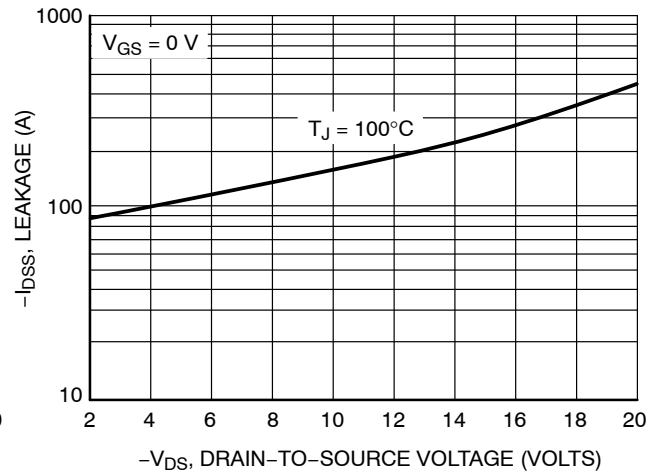
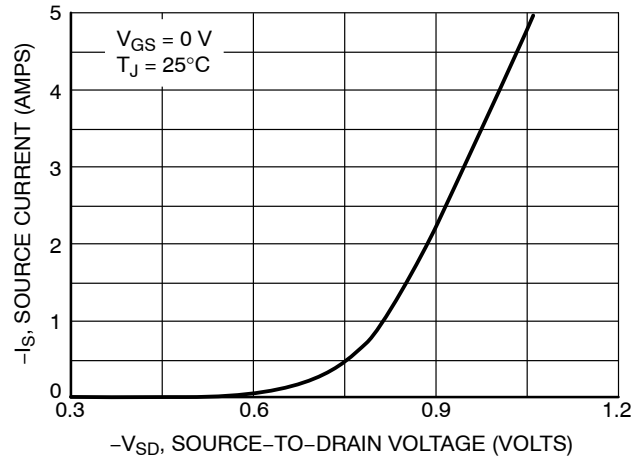
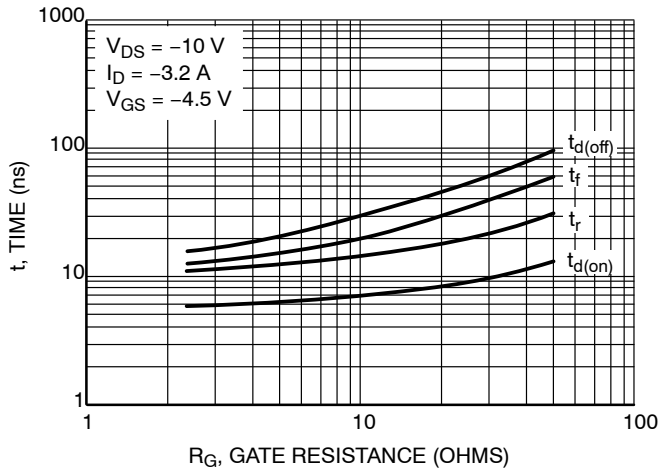
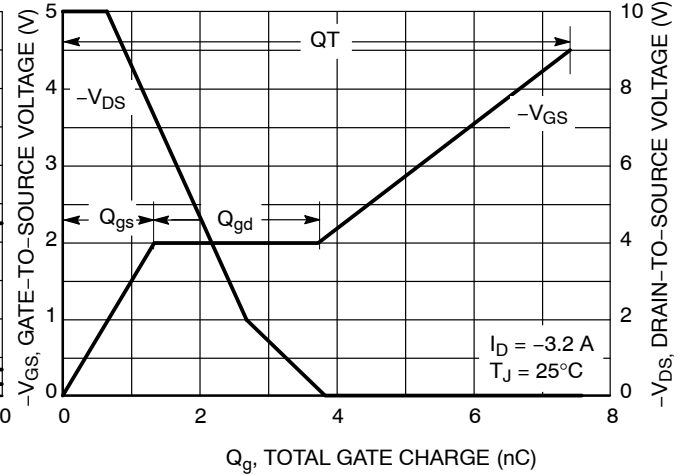
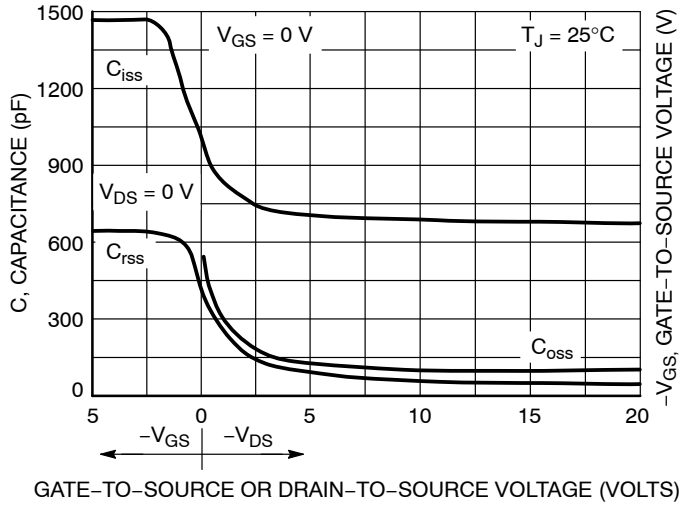


Figure 16. Drain-to-Source Leakage Current vs. Voltage

NTHD3100C

TYPICAL P-CHANNEL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)



DEVICE ORDERING INFORMATION

Device	Package	Shipping [†]
NTHD3100CT1	ChipFET	3000 / Tape & Reel
NTHD3100CT1G	ChipFET (Pb-Free)	3000 / Tape & Reel
NTHD3100CT3	ChipFET	10000 / Tape & Reel
NTHD3100CT3G	ChipFET (Pb-Free)	10000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

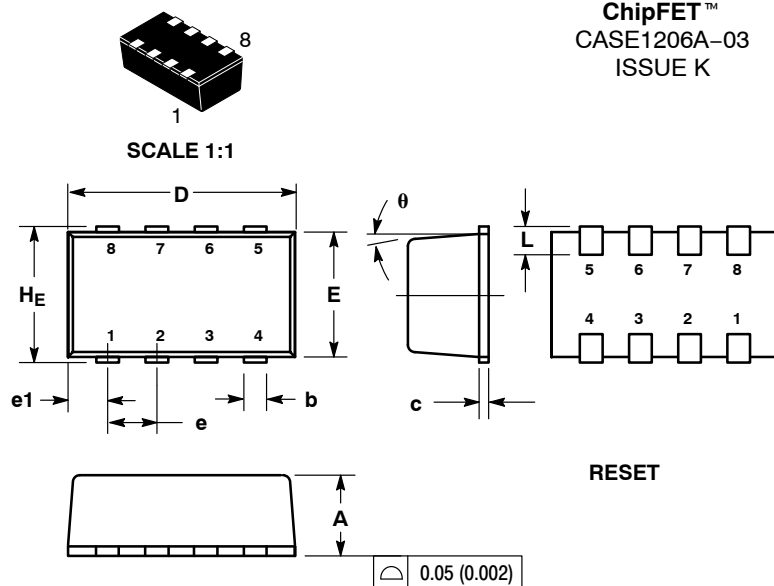
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



ChipFET™
CASE1206A-03
ISSUE K

DATE 19 MAY 2009



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MOLD GATE BURRS SHALL NOT EXCEED 0.13 MM PER SIDE.
4. LEADFRAME TO MOLDED BODY OFFSET IN HORIZONTAL AND VERTICAL SHALL NOT EXCEED 0.08 MM.
5. DIMENSIONS A AND B EXCLUSIVE OF MOLD GATE BURRS.
6. NO MOLD FLASH ALLOWED ON THE TOP AND BOTTOM LEAD SURFACE.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.00	1.05	1.10	0.039	0.041	0.043
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	1.55	1.65	1.70	0.061	0.065	0.067
e	0.65 BSC			0.025 BSC		
e1	0.55 BSC			0.022 BSC		
L	0.28	0.35	0.42	0.011	0.014	0.017
H_E	1.80	1.90	2.00	0.071	0.075	0.079
theta	5° NOM			5° NOM		

STYLE 1:

- PIN 1. DRAIN
2. DRAIN
3. DRAIN
4. GATE
5. SOURCE
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 2:

- PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

STYLE 3:

- PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

STYLE 4:

- PIN 1. COLLECTOR
2. COLLECTOR
3. COLLECTOR
4. BASE
5. EMITTER
6. COLLECTOR
7. COLLECTOR
8. COLLECTOR

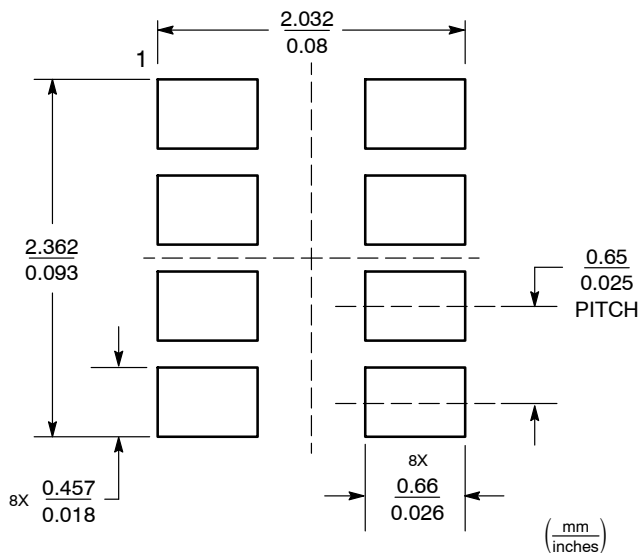
STYLE 5:

- PIN 1. ANODE
2. ANODE
3. DRAIN
4. DRAIN
5. SOURCE
6. GATE
7. CATHODE
8. CATHODE

STYLE 6:

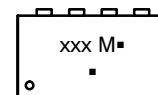
- PIN 1. ANODE
2. DRAIN
3. DRAIN
4. GATE
5. SOURCE
6. DRAIN
7. DRAIN
8. CATHODE / DRAIN

SOLDERING FOOTPRINT



Basic Style

GENERIC MARKING DIAGRAM*



- xxx = Specific Device Code
M = Month Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

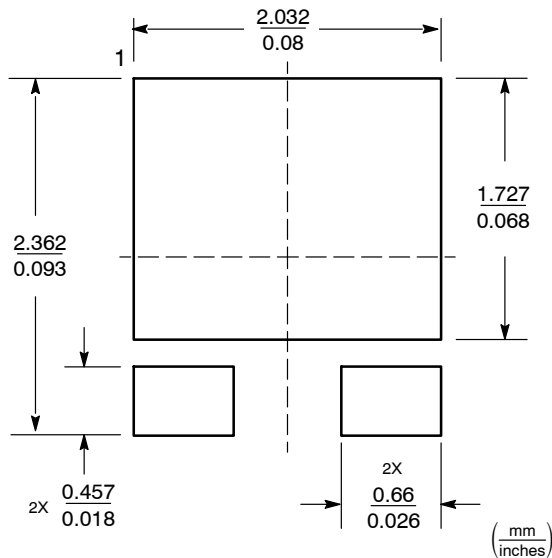
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

OPTIONAL SOLDERING FOOTPRINTS ON PAGE 2

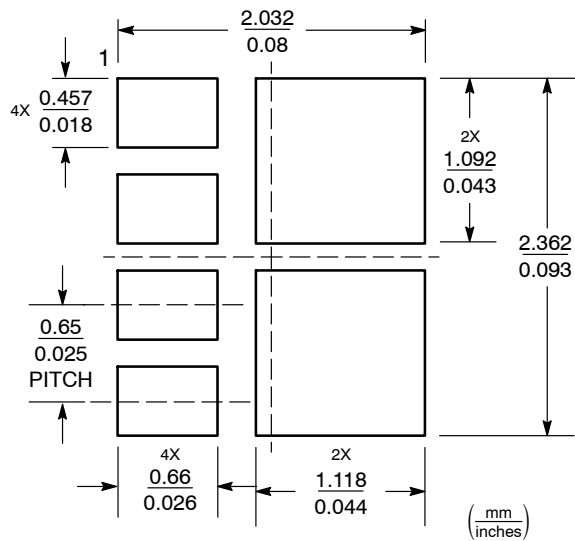
DOCUMENT NUMBER:	98AON03078D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	ChipFET	PAGE 1 OF 2

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

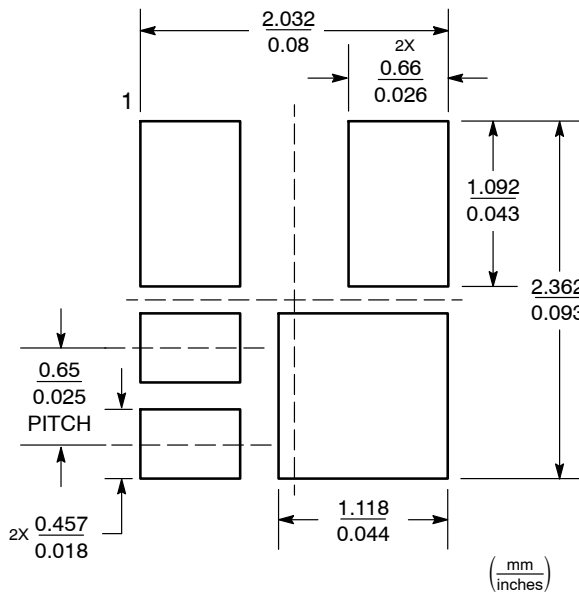
ADDITIONAL SOLDERING FOOTPRINTS*



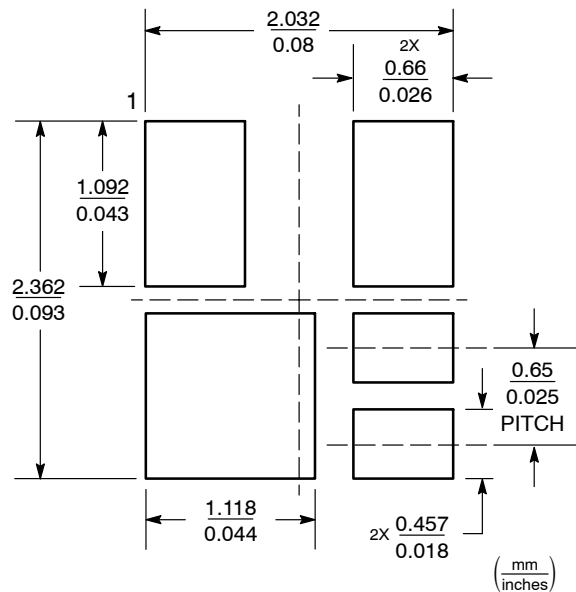
Styles 1 and 4



Style 2



Style 3



Style 5

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON03078D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	ChipFET	PAGE 2 OF 2

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative